

Notice of References Cited

Application N.

09/208962

Applicant(s)

Elco

Examiner

Abrams

Group Art Unit

2839

Pag ____ of ____

U.S. PATENT DOCUMENTS

| ☆ | DOCUMENT NO. | DATE | NAME | CLASS | SUBCLASS |
|---|--------------|---------|-------------------|-------|----------|
| A | 5593322 | 1-1997 | Swamy et al | 439 | 660 |
| B | 4767344 | 8-1988 | Noschese | 439 | 83 |
| C | 4695106 | 9-1987 | Feldman et al | 439 | 83 |
| D | 4678250 | 7-1987 | Romine et al | 439 | 83 |
| E | 5046960 | 9-1991 | Fedder | 439 | 108 |
| F | 5,174,764 | 12-1992 | Kandybowski et al | 439 | 81 |
| G | 5,120,232 | 6-1992 | Korsunsky | 439 | 108 |
| H | 5,258,648 | 11-1993 | Lin | 257 | 747 |
| I | 4,679,889 | 7-1987 | Seidler | 439 | 876 |
| J | | | | | |
| K | | | | | |
| L | | | | | |
| M | | | | | |

FOREIGN PATENT DOCUMENTS

| ☆ | DOCUMENT NO. | DATE | COUNTRY | NAME | CLASS | SUBCLASS |
|---|--------------|------|---------|------|-------|----------|
| N | | | | | | |
| O | | | | | | |
| P | | | | | | |
| Q | | | | | | |
| R | | | | | | |
| S | | | | | | |
| T | | | | | | |

NON-PATENT DOCUMENTS

| ☆ | DOCUMENT (Including Author, Title, Source, and Pertinent Pages) | DATE |
|---|--|---------|
| U | Teka "Solder-Bearing Lead (SBL) Series, Interplex Industries Co. | 8-1986 |
| V | Sized Solder Bumps make solid joints, Electronics, page 46 | 11-1981 |
| W | | |
| X | | |

* A copy of this reference is not being furnished with this Office action.
(See Manual of Patent Examining Procedure, Section 707.05(a).)